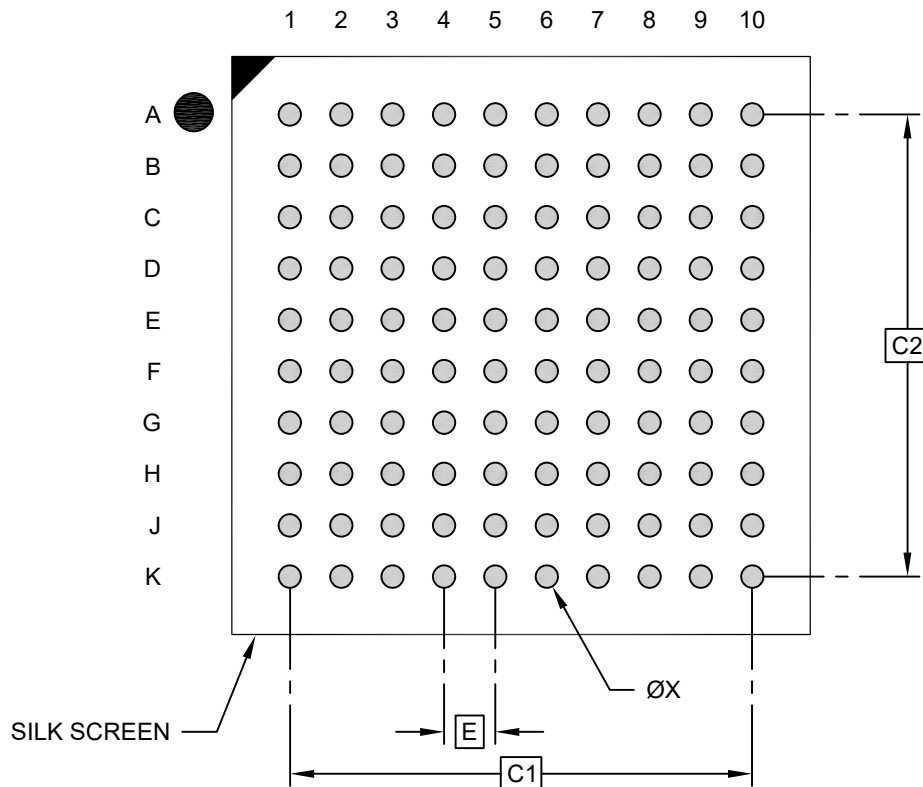


100-Ball Plastic Thin, Fine Pitch Ball Grid Array Package (HJB) - 9x9 mm Body [TFBGA] Atmel Legacy Global Package Code CPR

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.58 BSC		
Overall Pitch	C1	7.20 BSC		
Contact Pad Spacing	C2	7.20 BSC		
Contact Pad Diameter (X100)	X1			0.35

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. Supersedes C04-23111 and C04-23503